

Premium Vacuum Vapor Phase Machine

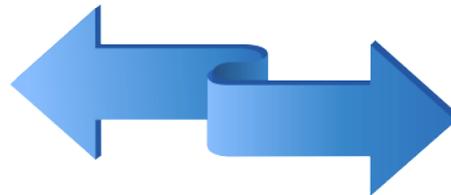
For Highest Challenges

VAC745/765



The **VAC 745/765** (available as batch or inline) combines the advantages of the vapor phase with the vacuum process and guarantees **void-free solder joints** with highest quality. The soldering system operates in a completely **inert atmosphere during the whole reflow and vacuum process**. Many patented features are available and provide a wide range of flexibility. The machine promises oxygen-free soldering and no overheating of components. In addition, the power consumption of the machine is very low.

- ✓ *Comfortable operation with 15" Touch Windows HMI Screen*
- ✓ *Permanent data collection with integrated Windows-PC*
- ✓ *Unlimited program memory*
- ✓ *Wide variety of adjustable solder profiles*
- ✓ *Low fluid consumption with 2-chamber design and medium recovery*
- ✓ *Integrated cooling fan*
- ✓ *Minimum maintenance and wear due to „cool handling“ (all moving parts outside the process chamber)*
- ✓ *4 internal temperature-sockets for external plugging of measuring devices*
- ✓ *Energy management system*
- ✓ *Medium level check*
- ✓ *Automatic medium filtering*
- ✓ *Automatic carrier in- and output*
- ✓ *Network capability*



Options

- RCS Rapid Cooling System (*patented*)
- IR heater system (*patented*)
- TRS – Temperature recording software and analysis for convenient documentation and fine adjustment of the process
- Barcode-system for automatic program change, traceability
- Measurement channels for board temperature recording
- Multi-Level-Mode for easy changeover between different solder heights
- Adapter for double sided PCB's
- UPS, uninterruptible power supply
- Inline-handling (*patented*)
- Closed-loop-chiller
- Additional cooling fan
- IPSC – Pilot-mode for temperature controlled soldering process incl. measurement channel for PCB-Temperature recording
- Heater element monitoring

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Technical Data	VAC745	VAC745i	VAC765	VAC765i
Length	1355 mm	2040 mm	1355 mm	2040 mm
Depth	2400 mm	3040 mm	2810 mm	3450 mm
Height	1470 mm	1470 mm	1470 mm	1470 mm
Weight	1030 kg	1290 kg	1200 kg	1450 kg
Loading/unloading level		900 – 1000 mm		900 – 1000 mm
Max. board size batch (in mm)	635 x 444 x 70 mm	635 x 444 x 70 mm	635 x 644 x 70 mm	635 x 644 x 70 mm
Max. board size Inline (in mm)		630 x 400 x 55 mm		630 x 400 x 55 mm
Medium agent filling	40 kg		60 kg	
Water connection	1/2" / 2,5-5 bar, 5l/min		1/2" / 2,5-5 bar, 6l/min	
Max. heating capacity	10,4 kW		13 kW	
Ø power consumption/h	5,5 kW/h		5,8 kW/h	
Power supply	400/230 VAC, 50/60 Hz, 11kW		400/230 VAC, 50/60 Hz, 16kW	
Main fuse	32A, Typ "gL" or "C"			
External vacuum module	900 x 540 x 650 mm, 140 kg			

- Technical changes reserved -

SPECIAL FEATURES

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 IPS, Intelligent Profiling System incl.
 - Soft Vapor Temperature Control (SVTC), temperature regulated process
 - Pilot Mode, set-up and profiling in one step
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 Automatic monitoring of vacuum pressure
- 
 Built-in software profiling capability
- 
 Syncro-Mode

- 
 Lead-free and leaded soldering with one fluid only, with different maximum temperatures
- 
 Vacuum process in the vapor phase for void-free soldering (*patented*)
- 
 Easy access to process chamber
- 
 Maintenance-free transport system (*patented*)